

## ALPHA FLUITIN 1532

### No CLEAN CORED SOLDER WIRE

Type: J-STD-004 – ROM1 / IPC-SF-818-M3CN / ISO 12224 – 1.1.2 / DIN 8511-F-SW26

#### DESCRIPTION

Alpha Fluitin 1532 is an activated rosin cored solder wire developed for general hand soldering applications. The unique activator system offers good thermal stability at pre-soldering temperatures ensuring that Fluitin 1532 performs extremely well on parts and surfaces which present poor or difficult soldering conditions.

Fluitin 1532 leaves post-soldering residues that are hard and which can be safely left without the need to remove them. If the removal of residues is required then semi-aqueous or aqueous systems can be used effectively.

#### FEATURES & BENEFITS

- *Minimal, non-corrosive, clear and safe residues.*
- *Very fast wetting.*
- *Good spread characteristics.*
- *Pleasant pine smell.*
- *Ease of solderability.*
- *Provides good joint appearance.*

#### APPLICATION

Fluitin 1532 is suitable for use in any commercial no-clean hand soldering application that specifies compliance to J-STD-004 – ROM1 standard.

It is suited to such areas of industry (subject to the above criteria) as TV, Audio equipment, Video/DVD, Games box and all types of household appliances.

#### HINTS & TIPS ON SOLDERING IN GENERAL

Always remember that a soldered joint is formed by heating the parts to be soldered to a temperature in excess of the melting point of the alloy to be used – in hand soldering this is how a soldering iron is used. By feeding the cored wire onto the parts, the flux is able to flow and remove oxide films, whilst the solder creates a thin intermetallic bond which becomes the solder joint.

Note the following tips:

- Use a soldering iron bit size and form to suit the operation: small bits for soldering large components may prevent the formation of a joint or slow the process down.
- Always select wire diameters to suit both soldering iron bit and the parts/components to be soldered.
- Soldering irons systems should provide sufficient heat to satisfy the requirements of the points above.
- Cored solder wires can be provided in different grades of alloy so always ensure you have selected the right grade for the application.
- Do not overheat as this causes an increase in the depth of the intermetallic layer, which in turn weakens the joint.



**Cookson Electronics** ASSEMBLY MATERIALS



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All materials from Cookson Electronics Assembly Material are manufactured to meet the most stringent of standards and to ensure the best possible finish to every soldering application.

**TECHNICAL SPECIFICATION**

Physical Properties	Typical Values	Standard	Alloy Designation	Melting or Solidus / Liquidus Temp °C	Flux Configuration
Rosin Grade:	WW per Fed Spec. LL-R-626	ISO 9453 (1)	-Sn63Pb37	183	1.1% & 2.2%
Rosin Softening Point:	71°C (160°F)	ISO 9453 (2)	S-Sn60Pb40	183 - 190	1.1% & 2.2%
Acid Value:	170-190 (mg KOH/g)	ISO 9453 (25)	S-Sn60Pb38Cu2	183 - 190	1.1% & 2.2%
Halide Content:	0.80 – 1.10% (by weight)	ISO 9453 (30)	S-SN62Pb36Ag2	178 - 190	2.2%
Corrosiveness:	Classified to J-STD-004 as M type material	LEAD FREE	SAC 305 LEAD FREE	217	2.2% & 3.3%
Copper Mirror:	Classified to J-STD-004 as <50% breakthrough	LEAD FREE	SACX0307 LEAD FREE	217 - 228	2.2% & 3.3%
Surface Insulation Resistance: (Not Cleaned)	Passes IPC-SF-818 Class III. Test results to J-STD-004 85°C/85% RH / 7 days CD = 4.7E10 Ohms CU = 5.9E09 Ohms (Pass > 1E08 Ohms)	LEAD FREE	SAC 405	217-219	2.2% & 3.3%
		LEAD FREE	Sn99Cu1	230-240	2.2% & 3.3%
Classification:	J-STD-004 – ROM1 IPC-SF-818 – M3CN ISO 12224 – 1.1.2. Din 8511 – F – SW26				

**HEALTH & SAFETY**

Observe standard precautions for handling and use. Use in well ventilated areas. **DO NOT SMOKE.**

Alpha Fluitin 1532 wire is not considered toxic. However, its use in typical soldering applications will generate a small amount of decomposition and fumes.

These fumes **must** adequately exhausted/vented for operator safety and comfort.

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In order to carry out your full COSHH assessment, consult the product Material Safety Data Sheet (MSDS).

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**European Headquarters:**

Cookson Electronics Assembly Materials  
Forsyth Road, Sheerwater  
Woking, Surrey  
GU21 5RZ. United Kingdom  
Tel: +44 (0) 1483 793100  
Fax: +44 (0) 1483 793101

**Worldwide Headquarters**

Cookson Electronics Assembly Materials  
600 Route 440  
Jersey City, New Jersey 07304  
USA  
Tel: +1 (201) 434 6778  
Fax: +1 (201) 434 7508

**Regional Offices**

Belgium:	Tel: +32 (0) 14 44 50 00
France:	Tel: +33 (0) 2 41 49 00 11
Germany:	Tel: +49 (0) 2173 8490 300
Ireland:	Tel: +353 (0) 1 842 1172
Italy:	Tel: +39 (0) 2 38 33 11
Hungary:	Tel: +36 (0) 24 460 720
Netherlands:	Tel: +31 (0) 35 695 5411

[www.alphametals.com](http://www.alphametals.com)

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